

**YAMA0347USB****Serial No. 09/525,247**

which new claims 16-20 were added to original claims 1-15. On October 17, 2000, the Examiner in this application mailed an Office Action, applying a Restriction Requirement to claims 1-15. No mention was made of claims 16-20.

Upon entry of the Preliminary Amendment, claims 1-20 are pending in the present application. Applicants respectfully request withdrawal of the Office Action mailed on October 17, 2000, and issuance of a new Office Action which is applicable to all the claims in this application.

**Proof of Filing of Preliminary Amendment**

A copy of the Preliminary Amendment filed on May 22, 2000, including Applicants' PTO SB/21 Transmittal Form, is included with this Letter. As shown on both the Certificate of Mailing on the Preliminary Amendment itself, and on the Transmittal Form Certificate of Mailing, the Preliminary Amendment was deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231 on May 22, 2000.

The Preliminary Amendment was received by the USPTO OIPE on May 25, 2000, as shown by Applicants' Postcard Receipt, an enlarged copy of which is included with this Letter.

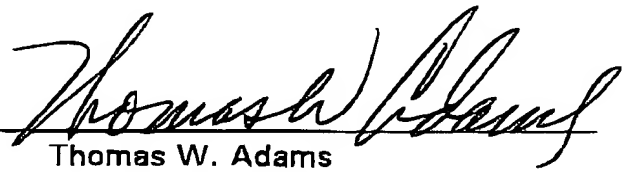
Applicants have shown by the foregoing facts that the Preliminary Amendment was in fact filed on May 22, 2000, and was received by the USPTO on May 25, 2000. Accordingly, Applicants respectfully request entry of the Preliminary Amendment filed on May 22, 2000, and issuance of a new Office Action which takes into account all pending claims, to replace the Office Action mailed on October 17, 2000.

This Letter is submitted in furtherance of a telephone conversation between Applicants' undersigned attorney, and S.P.E. Michael Gellner of Technology Center 2800, on November 14, 2000. To the extent necessary, this Letter constitutes Applicants' memorialization of this telephone conversation.

**YAMA0347USB****Serial No. 09/525,247**

Should the Examiner feel that a telephone interview would be helpful to facilitate favorable prosecution of the above-identified application, the Examiner is invited to contact the undersigned at the telephone number provided below. If any additional fees are required for the filing of these papers, Applicants request the Commissioner to charge those fees to deposit account #18-0988.

Respectfully submitted,  
RENNER, OTTO, BOISSELLE & SKLAR, P.L.L.

By   
Thomas W. Adams  
Reg. No. 35,047

1621 Euclid Avenue  
Nineteenth Floor  
Cleveland, Ohio 44115  
(216) 621-1113

B:\137\TWA\Client Files\YAMA\347b\YAMA347B.resubmitPA.wpd



COPY

YAMA0347USB

Serial No. 09/525,247

interposing at least one conductive pattern between at least one pair of insulation layers so as to be in contact with at least one of the pair of insulation layers; and

forming a conductive coil,

wherein the interposing step includes electroforming at least one conductive pattern, and no specific gap is formed between the conductive pattern and the pair of insulation layers [has a thickness of 10  $\mu\text{m}$  or more and a width to thickness ratio from 1 to less than 5].

17. The lamination chip inductor according to claim 16, wherein the conductive pattern has a width in the range from about 30  $\mu\text{m}$  to about 70  $\mu\text{m}$ , and a thickness in the range from about 20  $\mu\text{m}$  to about 50  $\mu\text{m}$ .

18. A lamination ceramic chip inductor, formed by the process comprising the steps of:

forming a conductive coil by electroforming at least one conductive pattern;

interposing said at least one conductive pattern between at least one pair of insulation layers so as to be in contact with at least one of the pair of insulation layers;

laminating the conductive coil between said at least one pair of insulation layers to form an integral body; and

sintering the integral body to form said lamination chip inductor;

whereby in the lamination ceramic chip inductor no specific gap is formed at interfaces between the conductive pattern and said insulation layers when the integral body is sintered.

19. The lamination ceramic chip inductor of claim 18, wherein the width of said conductive pattern is in the range from about 30 micrometers to about 70 micrometers

**YAMA0347USB****Serial No. 09/525,247**

and the thickness of said conductive pattern is in the range from about 20 micrometers to about 50 micrometers.

20. The lamination ceramic chip inductor of claim 19, comprising a plurality of lamination layers connected together via through holes formed in at least one of the insulation layers.

**REMARKS**

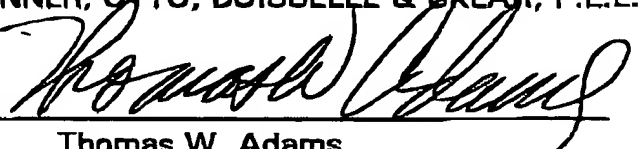
Upon entry of the present amendment, claims 1-20 are pending in the present application. The newly submitted claims 16-20 include two additional independent claims, and the appropriate fee is included herewith.

Newly submitted claims 16-20 are supported in the claims and specification of the parent application as originally filed, and at page 26, lines 7-14 of the present specification. No new matter is added by these amendments.

Should the Examiner feel that a telephone interview would be helpful to facilitate favorable prosecution of the above-identified application, the Examiner is invited to contact the undersigned at the telephone number provided below. If any additional fees are required for the filing of these papers, Applicants request the Commissioner to charge those fees to deposit account #18-0988.

Respectfully submitted,  
RENNER, OTTO, BOISSELLE & SKLAR, P.L.L.

By

  
Thomas W. Adams  
Reg. No. 35,047

1621 Euclid Avenue  
Nineteenth Floor  
Cleveland, Ohio 44115  
(216) 621-1113  
L:\109\TWA\YAMA\347\YAMA347B.preamd.wpd

**COPY**

COPY

Applicant Brito, et al. Case No. YAB/KP034709B  
Serial No. 09/525,247 Filing Date 3/15/00 Att. NAB/HDS/TWA  
Title IMPROVED AND METHOD FOR PRODUCING THE SAME  
Mailed 5/22/00 Due Date          Ex. Mail No.         

( ) Patent Application (          New          CON          DIV          CIP          CPA          PCT          Provisional)  
             Transmittal/Request          Declaration/Power of Atty          Issue Fee Trans.  
             Pages of Specification          Assignment & Cover Sheet          Main. Fee Trans.  
             Sheets of Drawings          Small Entity Statement          Lit. Off. Draftsman  
             Formal          Informal          IDS/1449/Refs.          Notice of Appeal  
             Pages of Abstract          Priority Document(s)          Appeal Brief  
(   X   ) Amendment/Response          Checks \$ 50. \$           
      X   Transmittal          Ext. of Time          \$           
( ) Trademark/Service App.           
             Specimens          St. of Use           
( ) Other         

**RECEIPT ACKNOWLEDGED**

**MAILED**  
MAY 25 2000  
PATENT & TRADEMARK OFFICE

COPY